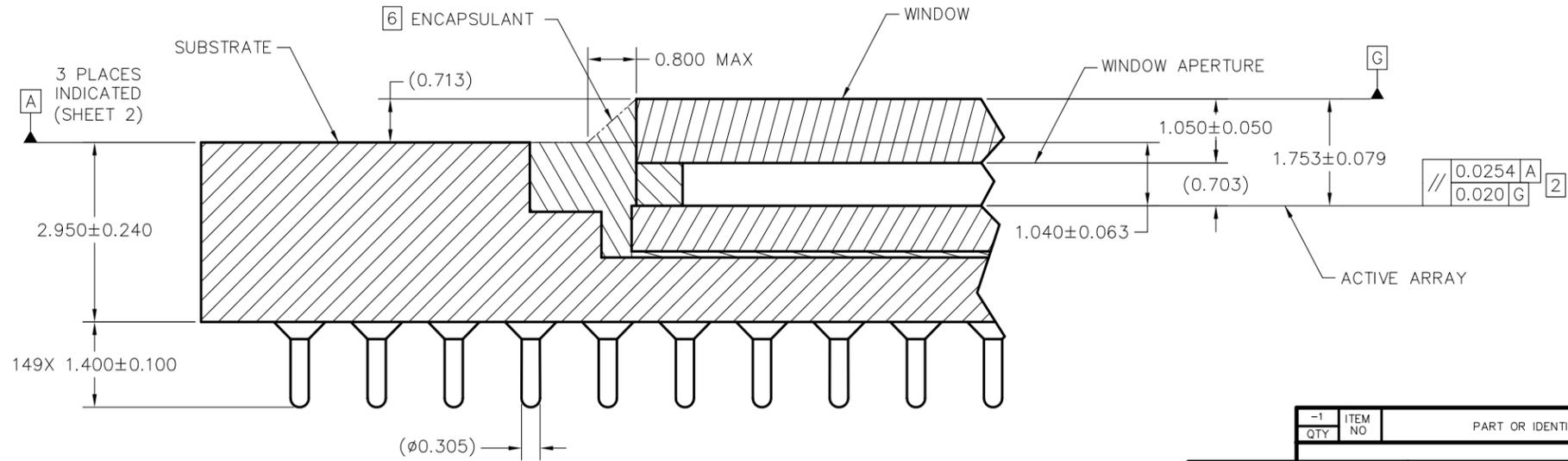
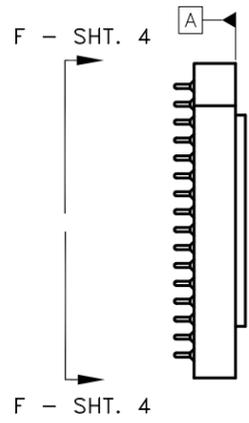
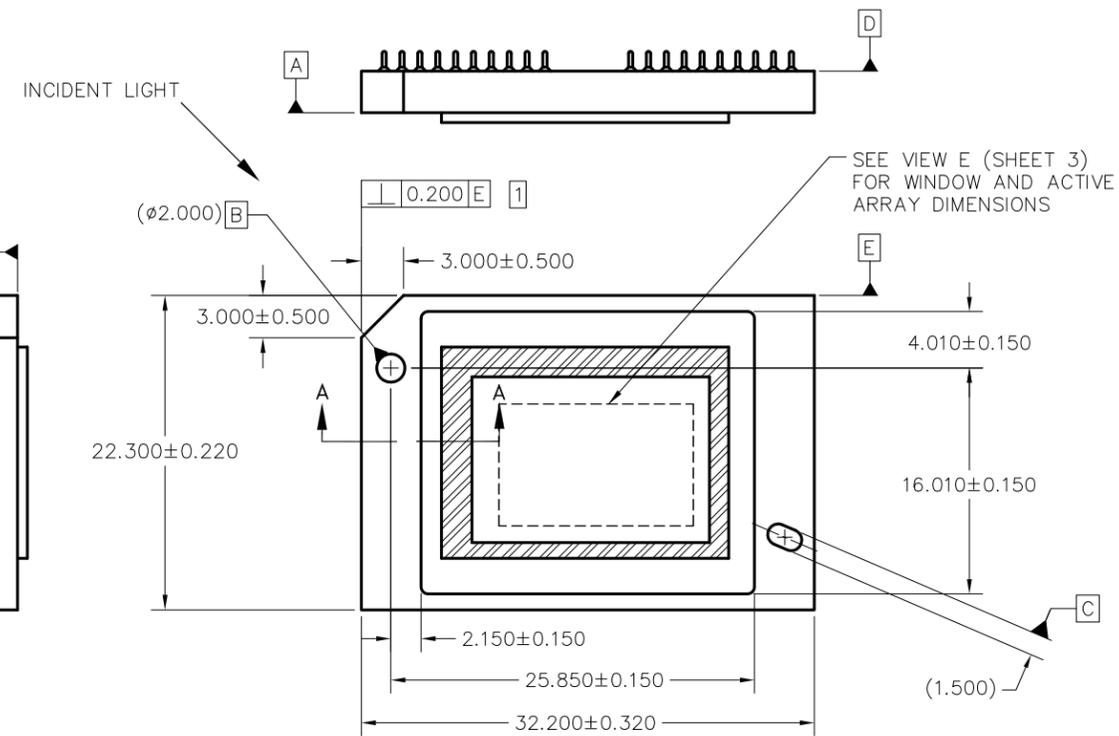


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2022283, INITIAL RELEASE	02/07/12	F. ARMSTRONG
B	ECO 2123271, CHG TO LARGE SYMBOLIZATION PAD	03/16/12	F. ARMSTRONG
C	ECO 2135104, ADD NOTE 8 TO SHEETS 1 & 4	08/02/13	F. ARMSTRONG
D	ECO 2168423, ADD FYL PACKAGE TO TITLE	08/17/17	M. AVERY

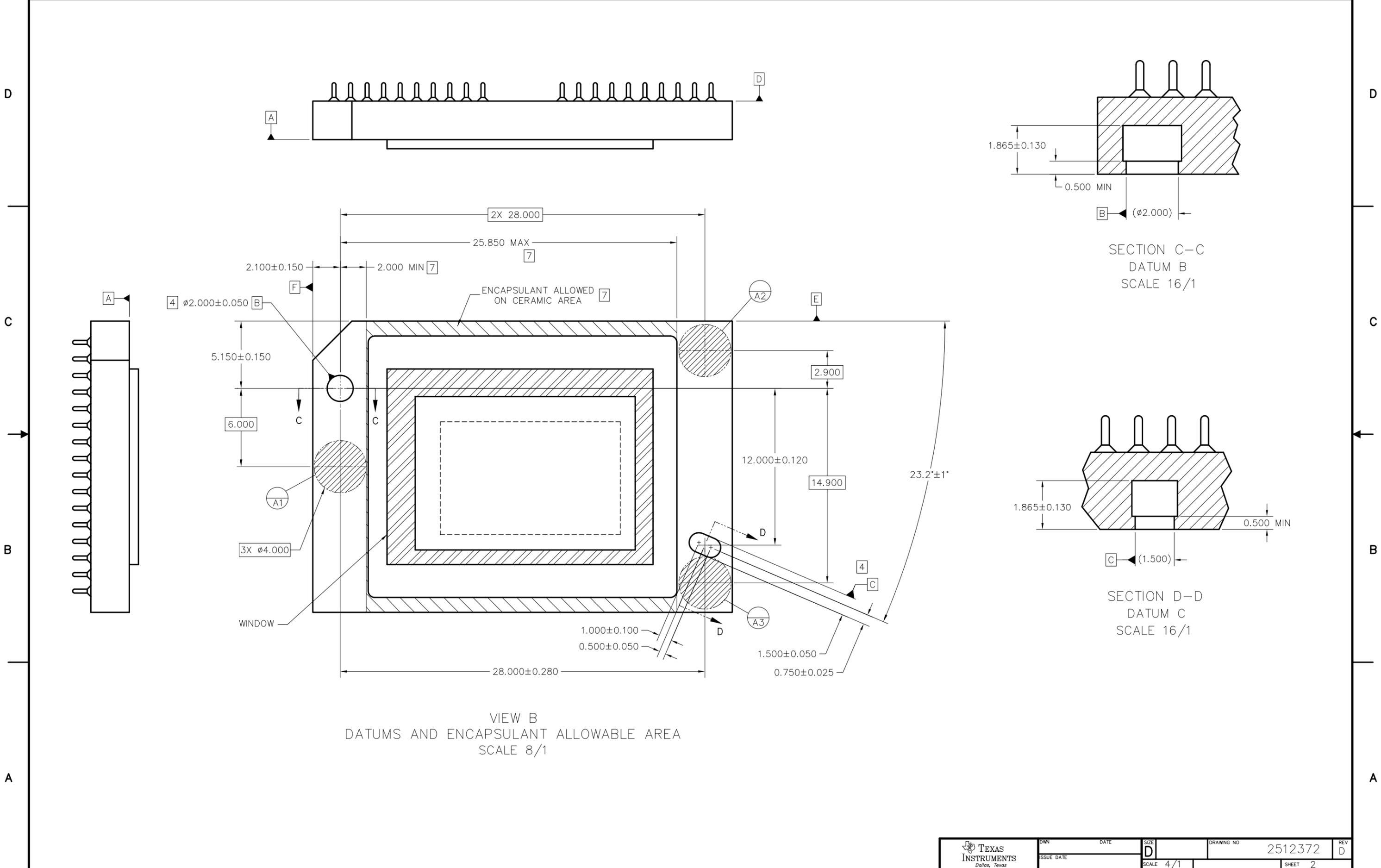
NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD, AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 5 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA ABOVE THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA BELOW THE SYMBOLIZATION PAD.



SECTION A-A
SCALE 20/1

-1	ITEM	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
QTY	NO			
PARTS LIST				
	DWN	F. ARMSTRONG	DATE 02/07/12	
	ENGR	F. ARMSTRONG	DATE 02/07/12	
	QA	P. KONRAD		
	COE	M. DORAK		
THIRD ANGLE PROJECTION		NONE	0314DA	
	NEXT ASSY	USED ON		
	APPLICATION			
UNLESS OTHERWISE SPECIFIED		DIMENSIONS ARE IN MILLIMETERS		
TOLERANCES: ANGLES ± 1°		2 PLACE DECIMALS ±0.25		
		3 PLACE DECIMALS ±0.50		
REMOVE ALL BURRS AND SHARP EDGES		INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994		
DIMENSIONAL LIMITS APPLY BEFORE PROCESSES		PARENTHEICAL INFO FOR REF ONLY		
TEXAS INSTRUMENTS Dallas, Texas		ICD, MECHANICAL, DMD .65 WXGA-800 2xLVDS V2 SERIES 450 (FYL PACKAGE)		
SIZE	D	DRAWING NO	2512372	REV D
SCALE	4/1	SHEET	1 OF 4	



D

D

C

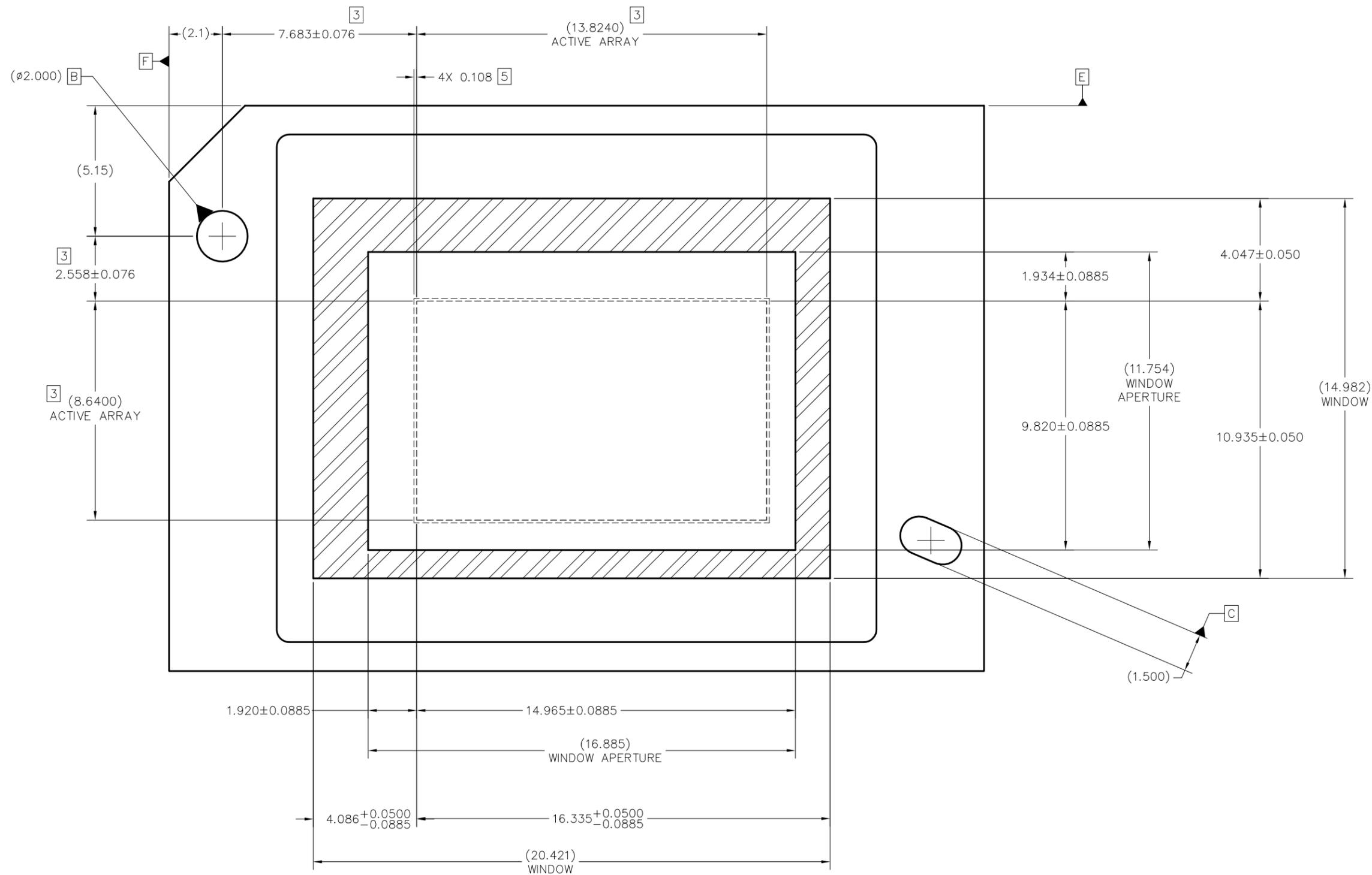
C

B

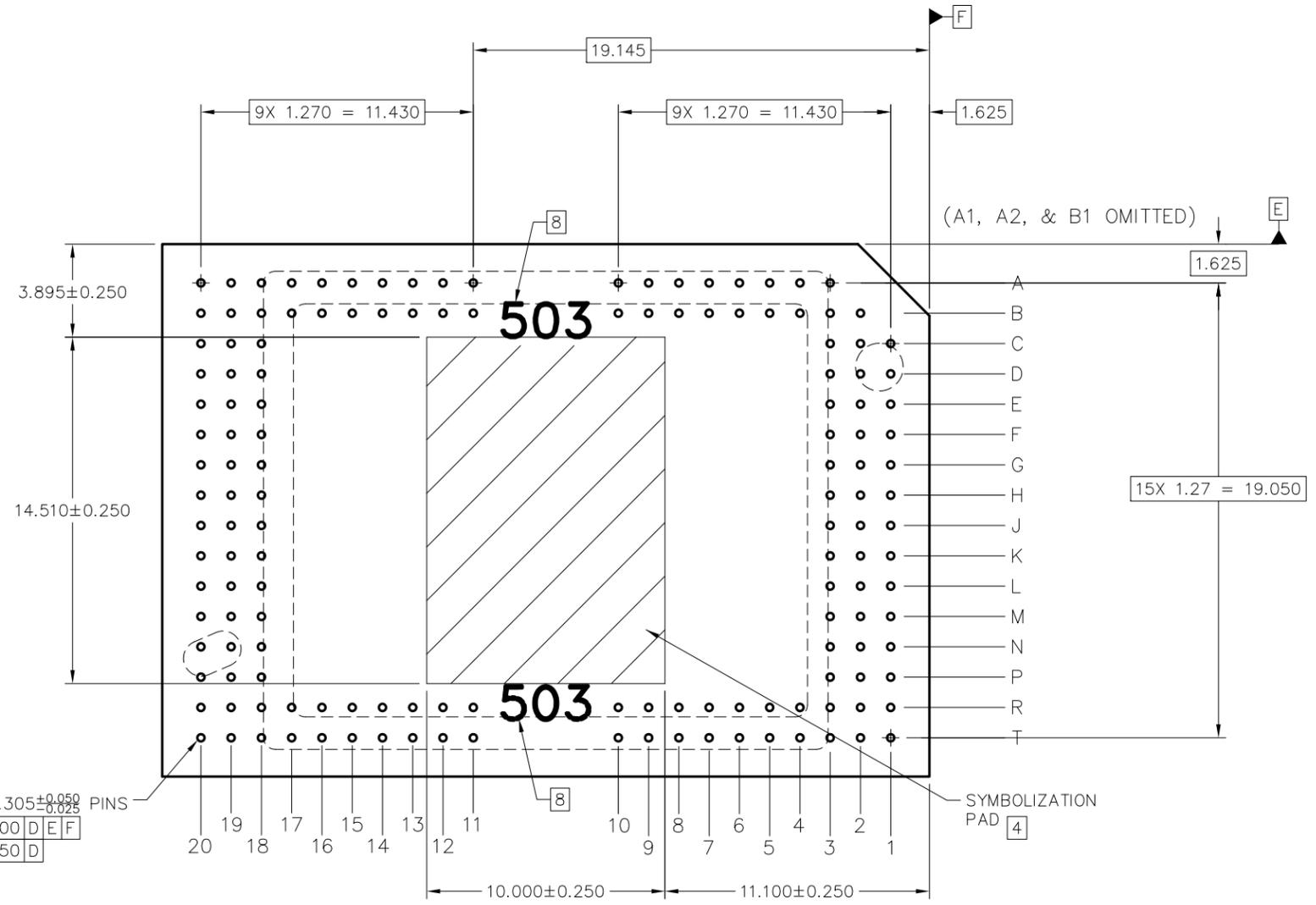
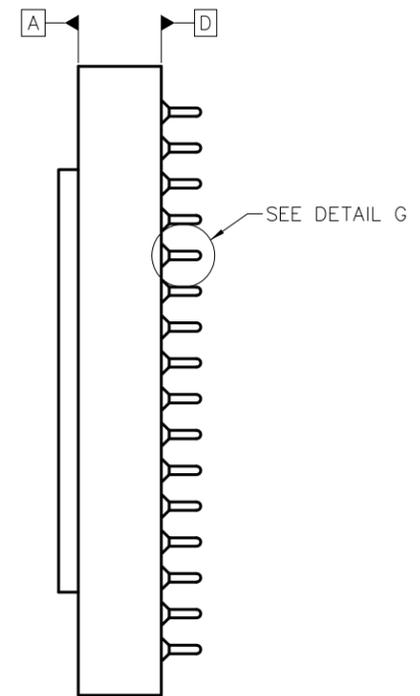
B

A

A



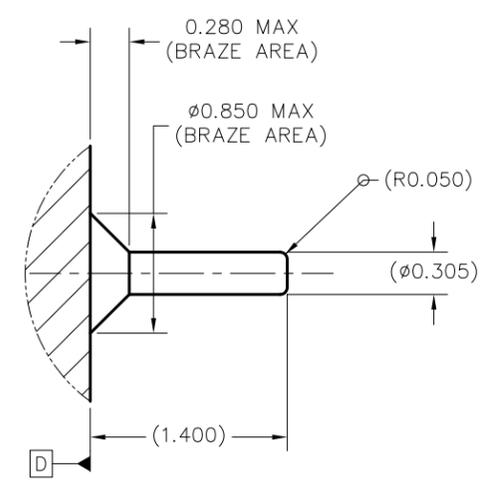
VIEW E (SHEET 1)
DMD WINDOW AND ACTIVE ARRAY
SCALE 12:1



149X $\phi 0.305 \pm 0.050$
 -0.025 PINS

$\phi 0.500$	D	E	F
$\phi 0.250$	D		

VIEW F-F (SHEET 1)
 PINS AND SYMBOLIZATION PAD
 SCALE 8/1



DETAIL G (149 PLACES)
 PIN & BRAZE DIMENSIONS
 SCALE 40/1

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